L Number	Hits	S arch Text	DB	Time stamp
-	0	(surface near (m unt r m uting r m unted) n ar (package or packaging)).ti,ab,clm. and (l d or (light near miting n ar (diod or d vi))).ti,ab, lm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and substrate.ti,ab,clm.	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:27
-	0	(surface near (mount or mouting or mounted) near (package or packaging)).ti,ab,clm. and (led or (light near emitting near (diode or device))).ti,ab,clm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and substrate.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:28
-	74	(surface near (mount or mouting or mounted) near (package or packaging)) and (led or (light near emitting near (diode or device))) and (seal or sealing or adhesive) and (solder or soldering) and (metal or gold or silver or conductive or conducting) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:28
-	9	(surface near (mount or mounting or mounted)).ti,ab,clm. and (led or (light near emitting near (diode or device))).ti,ab,clm. and (seal or sealing or adhesive).ti,ab,clm. and (solder or soldering).ti,ab,clm. and (metal or gold or silver or conductive or conducting).ti,ab,clm. and substrate.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:30
-	613	(surface near (mount or mounting or mounted)).clm. and (led or (light near emitting near (diode or device))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:30
-	6	(surface near (mount or mounting or mounted)).clm. and (led or (light near emitting near (diode or device))).clm. and ((first or upper or lower or top or bottom or two) near (gold or silver or metal or conductive or conducting) near layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:34
-	3	(surface near (mount or mounting or m unt d)) near5 (l d or (light n ar emitting near (di de or devic))). lm. and ((first or upp r r l wer or t p or b ttom r tw) n ar (g ld r silver or metal or condu tiv r conducting) n ar layer).clm.	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2004/06/22 15:34

-		3	((surface n ar (mount or m unting or m unted)) near5 (led or (light n ar mitting n ar (diod r device)))).clm. and ((first r upper or l wer or top r bott m or two) near (gold or silver or m tal r onductive or c nducting) near layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:35
-		3	((surface near (mount or mounting or mounted)) near5 (led or (light near emitting near (diode or device)))).clm. and ((first or upper or lower or top or bottom or two) near2 (gold or silver or metal or conductive or conducting) near layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:35
-		3	((surface near (mount or mounting or mounted)) near5 (led or (light near emitting near (diode or device)))).clm. and ((first or upper or lower or top or bottom or two) near2 (gold or silver or metal or conductive or conducting) near2 layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:36
-		3	((surface near (mount or mounting or mounted)) near10 (led or (light near emitting near (diode or device)))).clm. and ((first or upper or lower or top or bottom or two) near2 (gold or silver or metal or conductive or conducting) near2 layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:36
-		4	((surface near (mount or mounting or mounted)) near10 (led or (light near emitting near (diode or device)))).ti,ab,clm. and ((first or upper or lower or top or bottom or two) near2 (gold or silver or metal or conductive or conducting) near2 layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:36
-		6	((surface near (mount or mounting or mounted)) near10 (led or (light near emitting near (diode or device)))).ti,ab,clm. and ((first or upper or lower or top or bottom or two) near2 (gold or silver or metal or conductive or conducting) near2 layer).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:38
-		6	((surface near (mount or mounting or mounted)) near10 (led or (light near emitting near (diode or device)))).ti,ab,clm. and ((first or second or upper or lower or top or bottom or two) near2 (gold or silver or metal or conductive or conducting) near2 layer).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:38
-		952	((surface near (mount or mounting or mounted)) near10 (led or (light near emitting n ar (diode or device)))).ti,ab,clm.	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2004/06/22 15:40

-		16	((surface near (m unt r m unting or mount d)) n ar10 (l d r (light near mitting near (di de r d vice)))).ti,ab,clm. same ((metal or c nductive or ndu ting r gold r silver) near lay r).ti,ab, lm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:42
-		1	((surface near (m unt or m unting r mounted)) near10 (led or (light near emitting near (diode or device)))).clm. same ((metal or conductive or conducting or gold or silver) near layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:45
-		2	((surface near (mount or mounting or mounted)) near10 (led or (light near emitting near (diode or device)))).clm. same ((electrode or metal or conductive or conducting or gold or silver) near layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:46
-		4	((surface near (mount or mounting or mounted)) near10 (led or (light near emitting near (diode or device)))).clm. same ((electrode or metal or conductive or conducting or gold or silver) near (electrode or layer)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 15:47
-		393	((led or (light near emitting near (diode or device)))).clm. and ((second or two or upper or lower or top or bottom) near ((electrode or metal or conductive or conducting or gold or silver) near (electrode or layer))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:09
-		79	((led or (light near emitting near (diode or device)))).clm. and (substrate near10 ((second or two or upper or lower or top or bottom) near ((electrode or metal or conductive or conducting or gold or silver) near (electrode or layer)))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:10
-		7	(surface near (mount or mounting or mounted)).ti,ab,clm. and ((led or (light near emitting near (diode or device)))).clm. and (substrate near10 ((second or two or upper or lower or top or bottom) near ((electrode or metal or conductive or conducting or gold or silver) near (electrode or layer)))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:10
-		291	((surface near (mount or mounting or mounted)) near10 (led or (light near emitting))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:13
-		71	((surface n ar (m unt r mounting or m unt d)) near10 (l d or (light n ar mitting))).clm. and ((surfa e n ar (m unt r m unting r m unted)) n ar10 (led r (light near mitting))).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:17

-	3320	two near metal n ar layer	USPAT; US-PGPUB; EPO; JP ; DERWENT; IBM_TDB	2004/06/22 16:17
-	29	(two n ar metal near lay r) and (l d or (light near emitting)) and (surface near (mount or mounting or mounted))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:20
-	1	(two near metal near layer).clm. and (led or (light near emitting)) and (surface near (mount or mounting or mounted))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:20
-	10	(two near (silver or gold or conductive or conducting or electrode or metal) near layer).clm. and (led or (light near emitting)) and (surface near (mount or mounting or mounted))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:22
-	2285	(two near2 (silver or gold or conductive or conducting or electrode or metal) near layer) near10 (insulate or insulated or insulating or insulation or isolate or isolated or isolating or isolation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:23
-	280	((two near2 (silver or gold or conductive or conducting or electrode or metal) near layer) near10 (insulate or insulated or insulating or insulation or isolate or isolated or isolating or isolation)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:24
-	7371	(((second or first or upper or lower or top or bottom or two) near2 (silver or gold or conductive or conducting or electrode or metal) near layer) near10 (insulate or insulated or insulating or insulation or isolate or isolated or isolating or isolation)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:26
-	1779	(((second or first or upper or lower or top or bottom or two) near2 (silver or gold or conductive or conducting or electrode or metal) near layer) near10 (insulate or insulated or insulating or insulation or isolate or isolated or isolating or isolation) near10 substrate).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:25
-	2	((((second or first or upper or lower or top or bottom or two) near2 (silver or gold or conductive or conducting or electrode or metal) near layer) n ar10 (insulate or insulated or insulating r insulati n or isolat r is lated or isolating r isolati n)).clm. same (substrat) same (l d r (light near emitting)) same (surfa n ar (m unt or mounting r mounted))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/22 16:28